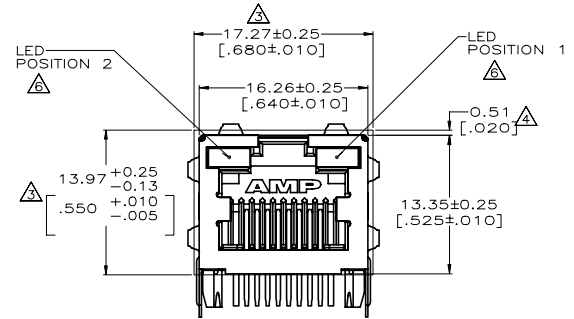
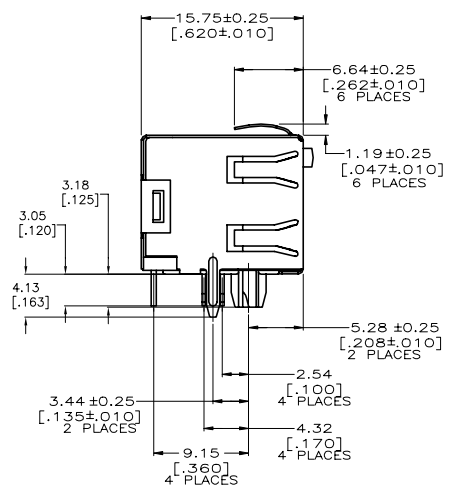
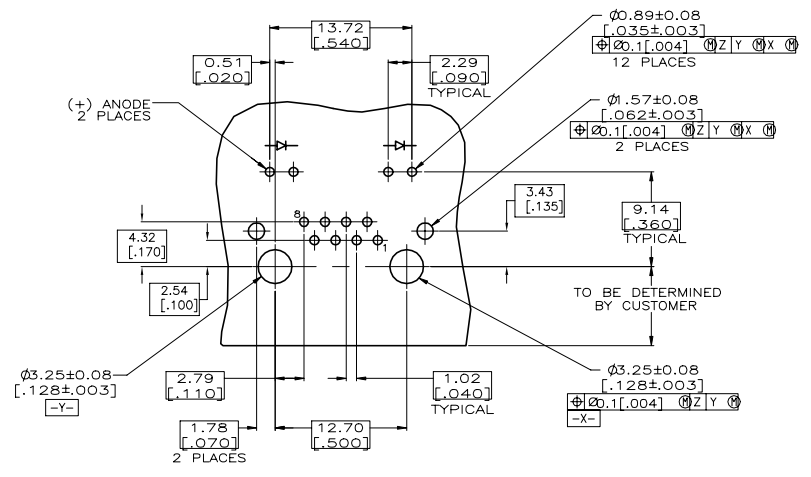
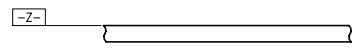


REVISIONS				
REV	DATE	DESCRIPTION	BY	APP'D
E1	29AUG2020	ECO-18-014918	RR	SH



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL (WIREFRAME LEADS) PREPLATED WITH 8.89µm[.000350] THICK TIN/COPPER OVER 2.03µm[.000080] THICK SILVER OVER 1.02µm[.000040] THICK COPPER OVER 3.56µm[.000140] THICK NICKEL OVER 1.02µm [.000040] THICK COPPER UNDERPLATE
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 0.051[.002] WHITE POLYESTER INSULATOR APPLIED TO BACK OF HOUSING.
  - SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
  - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



OBSOLETE	POSITION 1	POSITION 2	PART NUMBER
	INDICATOR COLOR		
	GREEN	GREEN	1116173-5
	GREEN	YELLOW	1116173-4
	YELLOW	GREEN	1116173-1

SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE: 25MAR18	REV: 25MAR18	TE Connectivity
DRAWN BY: STRAUSSER		DATE: 27MAR18	REV: 27MAR18	TE Connectivity
CHECKED BY: LAUBER		DATE: 27MAR18	REV: 27MAR18	TE Connectivity
APPROVED BY: LAUBER		DATE: 27MAR18	REV: 27MAR18	TE Connectivity
PRODUCT SPEC: 108-1163-4		APPLICATION SPEC: 114-2154		
MATERIAL: SEE NOTE 1		WEIGHT: 0.000000		SIZE: A1
SEE NOTE 1		DATE CODE: 100779		DRAWING NO: 1116173
CUSTOMER DRAWING		SCALE: 4:1		SHEET: 1 of 1